



*[Handwritten signature]* 5-13-02  
219.40606X00

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): **Scot A. KELLAR et al.**

Serial No.: **10/066,645**

Filed: **February 6, 2002**

For: **DIELECTRIC RECESS FOR WAFER-TO-WAFER AND DIE-TO-DIE  
BONDING AND METHOD OF FABRICATING THE SAME**

Group: **2811**

**INFORMATION DISCLOSURE STATEMENT**  
**UNDER 37 CFR §1.97 & §1.98**

Assistant Commissioner of Patents  
Washington, D.C. 20231

**April 16, 2002**

Sir:

In the matter of the above-identified application, Applicants are submitting herewith copies of the documents listed in the attached form equivalent to Form PTO-1449 for the Examiner's consideration.

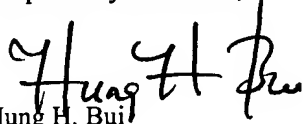
This information disclosure statement is being submitted within three months of the filing date.

Each of the documents listed on the attached form equivalent to Form PTO-1449 is in the English language.

It is respectfully requested that this information disclosure statement be considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper,  
including extension of time fees, to Deposit Account No. 01-2135 (219.40606X00) and please credit  
any excess fees to such deposit account.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Hung H. Bui". The signature is stylized with a large "H" and a cursive "Bui".

Hung H. Bui

Registration No. 40,415

ANTONELLI, TERRY, STOUT & KRAUS, LLP

HHB/srm  
Attachments  
(703) 312-6600